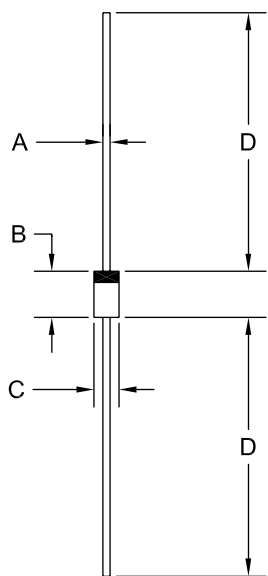


Package Details - DO-41

Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.028	0.034	0.71	0.86
B	0.160	0.205	4.06	5.21
C	0.080	0.107	2.03	2.72
D	1.000	-	25.40	-

DO-41 (REV: R1)

Lead Code:
Cathode band

R1

Packing options:

Bulk - Packing Code: D

D = White corrugated box with black conductive coating (surface resistivity of $<10^5$ ohms per square).

Bulk Packing Quantity: 2,000

Tape and Reel - Packing Code: A

A = Axial taped and reeled in accordance with EIA-296-E. If required, individual reels placed in poly antistatic coated bags (surface resistivity of $>10^9$ and $<10^{13}$ ohms per square).

Tape and Reel Packing Quantity: 5,000

Material Composition Specification

DO-41 Glass Case



Device average mass 335 mg

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.024%	0.08	Si	7440-21-3	0.017%	0.058	174
				Ag	7440-22-4	0.007%	0.022	66
leadframe	dumet	12.24%	41	Ni	7440-02-0	5.753%	19.271	57,525
				Fe	7439-89-6	4.529%	15.171	45,286
				Cu	7440-50-8	1.958%	6.561	19,584
	metal alloy	68.68%	230.08	Fe	7439-89-6	48.077%	161.058	480,769
Cu				7440-50-8	20.604%	69.026	206,044	
encapsulation	glass	16.63%	55.7	PbO	1317-36-8	9.977%	33.422	99,768
				SiO ₂	14808-60-7	6.651%	22.282	66,512
plating*	tin/lead process	2.4%	8.04	Sn	7440-31-5	1.92%	6.43	19,190
				Pb	7439-92-1	0.48%	1.61	4,805
	matte tin	2.4%	8.04	Sn	7440-31-5	2.4%	8.04	23,995
ink	N/A	0.028%	0.089	tributyl-phosphate	126-73-8	0.017%	0.056	168
				carbon black	1333-96-4	0.004%	0.013	38
				phenol	108-95-2	0.001%	0.001	14
				Proprietary	--	0.006%	0.019	58

*For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (16-June 2011)

Material Composition Specification

DO-41 Epoxy Case



Device average mass 336 mg

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.22%	0.75	Si	7440-21-3	0.22%	0.75	2,233
				Au	7440-57-5	0.001%	0.004	12
die attach	high temperature solder	0.63%	2.11	Pb	7439-92-1	0.58%	1.95	5,806
				Sn	7440-31-5	0.03%	0.104	310
				Ag	7440-22-4	0.02%	0.056	167
leadframe	metal alloy	82.55%	277.3	Fe	7439-89-6	0.07%	0.25	744
				Cu	7440-50-8	82.47%	277	824,724
encapsulation*	EMC	13.7%	46	SiO ₂	14808-60-7	9.31%	31.28	93,131
				epoxy resin	29690-82-2	2.74%	9.2	27,392
				phenol resin	9003-35-4	1.37%	4.6	13,696
				Sb ₂ O ₃	1309-64-4	0.14%	0.46	1,370
				Br	7726-95-6	0.14%	0.46	1,370
	EMC GREEN	13.7%	46	silica (fused)	60676-86-0	10.55%	35.42	105,457
				epoxy resin	29690-82-2	1.37%	4.6	13,696
				phenol resin	9003-35-4	1.33%	4.46	13,279
				carbon black	1333-86-4	0.04%	0.14	417
				aluminum hydroxide	1309-42-8	0.41%	1.38	4,109
plating**	tin/lead process	2.89%	9.71	Sn	7440-31-5	2.31%	7.77	23,134
				Pb	7439-92-1	0.58%	1.94	5,776
	100% tin process	2.89%	9.71	Sn	7440-31-5	2.89%	9.71	28,910
ink	N/A	0.01%	0.05	2-propenic acid	53192-18-0	0.01%	0.021	63
				Al	7429-90-5	0.002%	0.006	18
				silica	112945-52-5	0.0003%	0.001	3
				methanone	947-19-3	0.0003%	0.001	3
				isoamyl 4-benzoate	21245-01-2	0.01%	0.017	51

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

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R3 (3-June 2011)